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(54) **METHOD FOR MACHINING SEED RODS
FOR USE IN A CHEMICAL VAPOR
DEPOSITION POLYSILICON REACTOR**

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(21) Appl. No.: **13/417,792**

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(65) **Prior Publication Data**

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B24B 19/00 (2006.01)

B24B 7/16 (2006.01)

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B24B 19/009 (2013.01)

(58) **Field of Classification Search**

CPC **B24B 49/12**; **B24B 19/009**; **B24B 7/16**

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Translate.*

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(57)

ABSTRACT

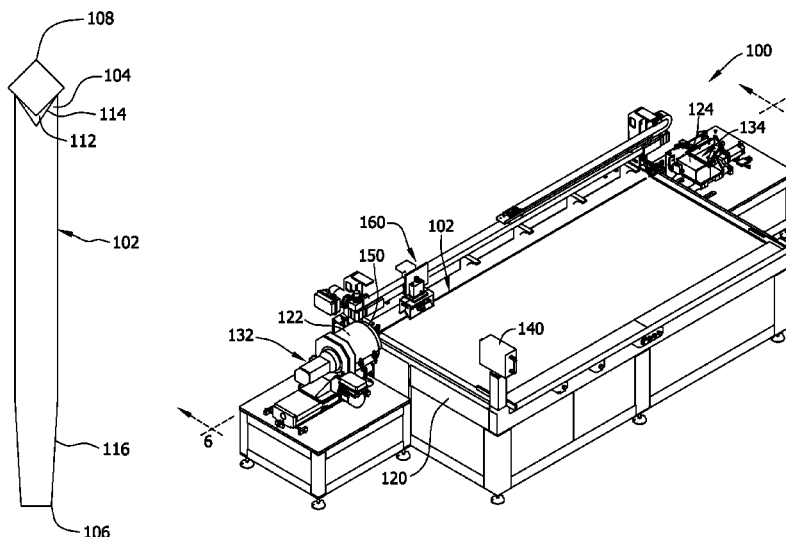
A method for machining a profile into a silicon seed rod using a machine. The silicon seed rod is capable of being used in a chemical vapor deposition polysilicon reactor. The machine includes a plurality of grinding wheels. The method includes grinding a v-shaped profile into a first end of the silicon seed rod with one of the plurality of grinding wheels and grinding a conical profile in a second end of the silicon seed rod with another of the plurality of grinding wheels.

13 Claims, 8 Drawing Sheets

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FIG. 1

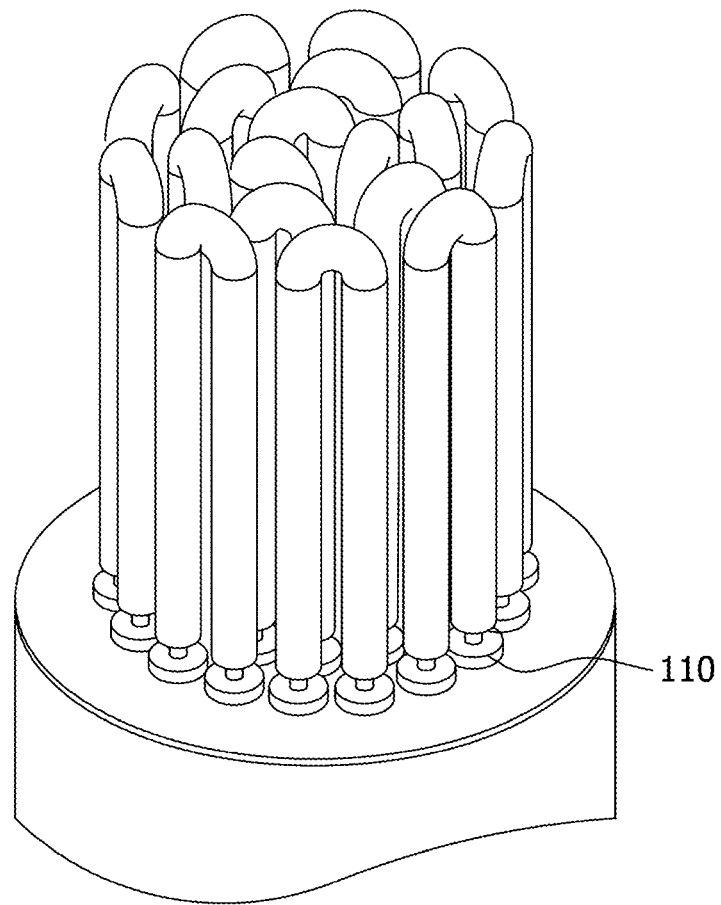


FIG. 2

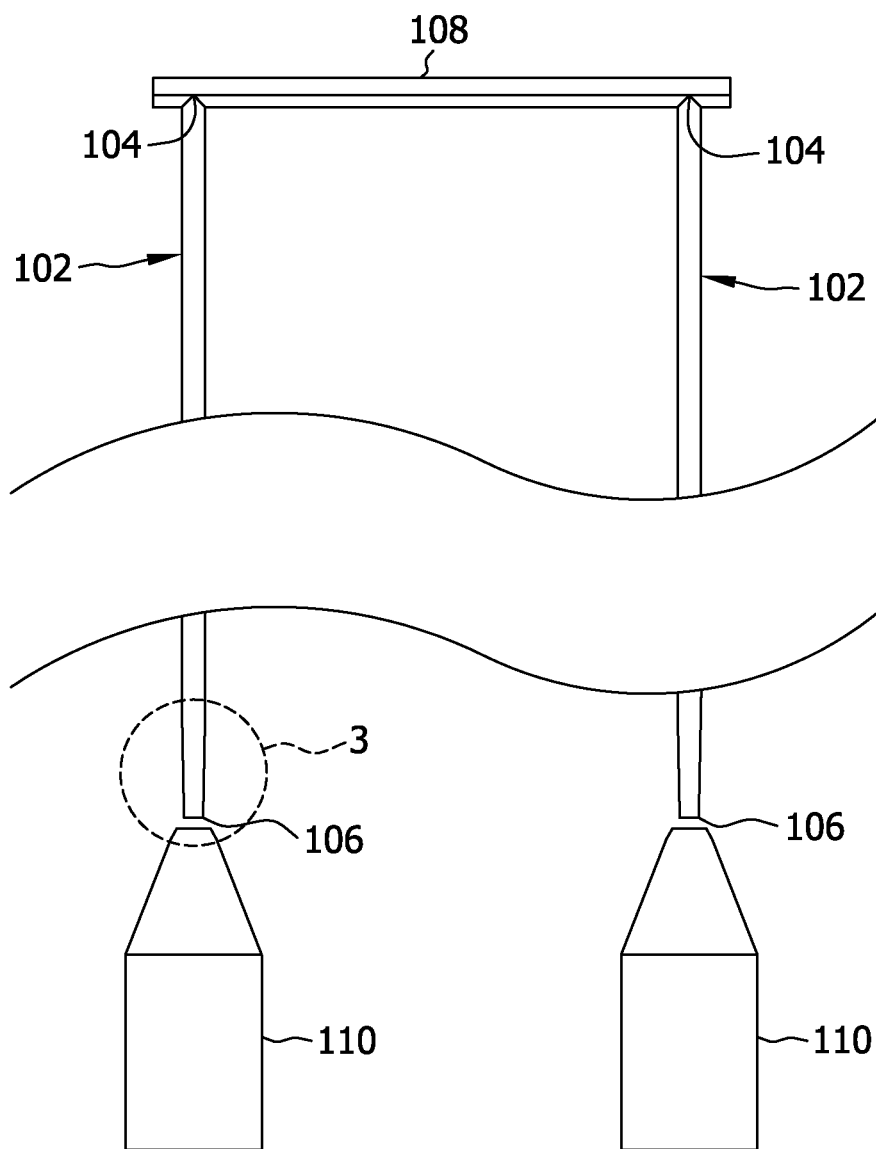


FIG. 3

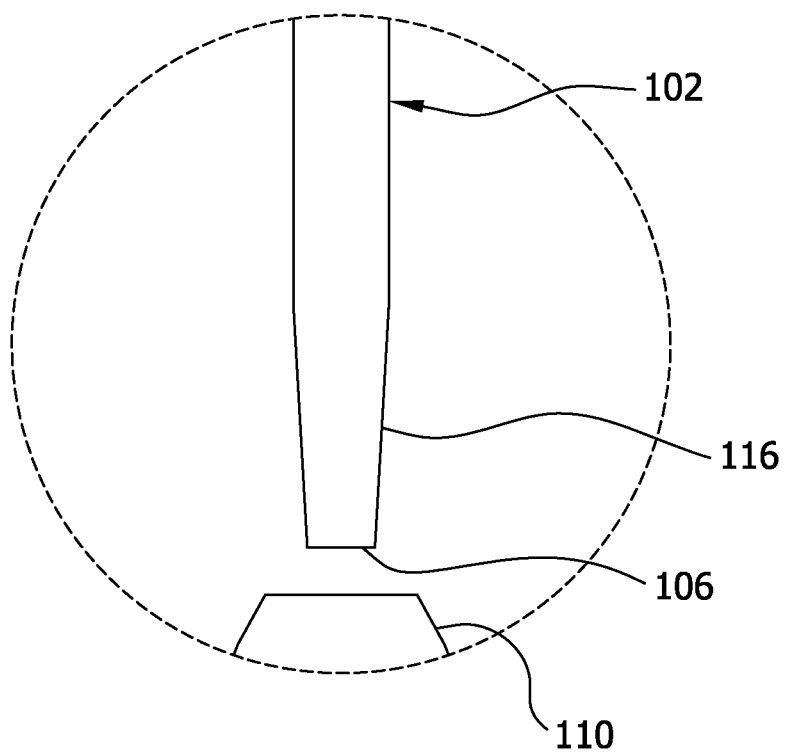


FIG. 4

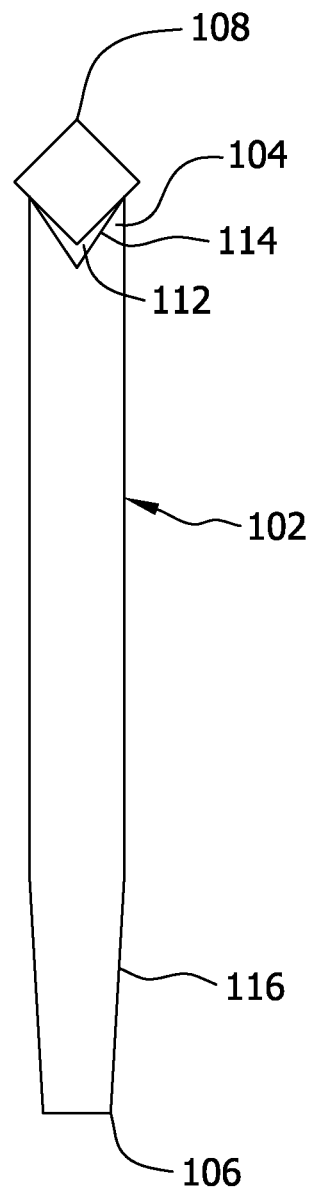


FIG. 5

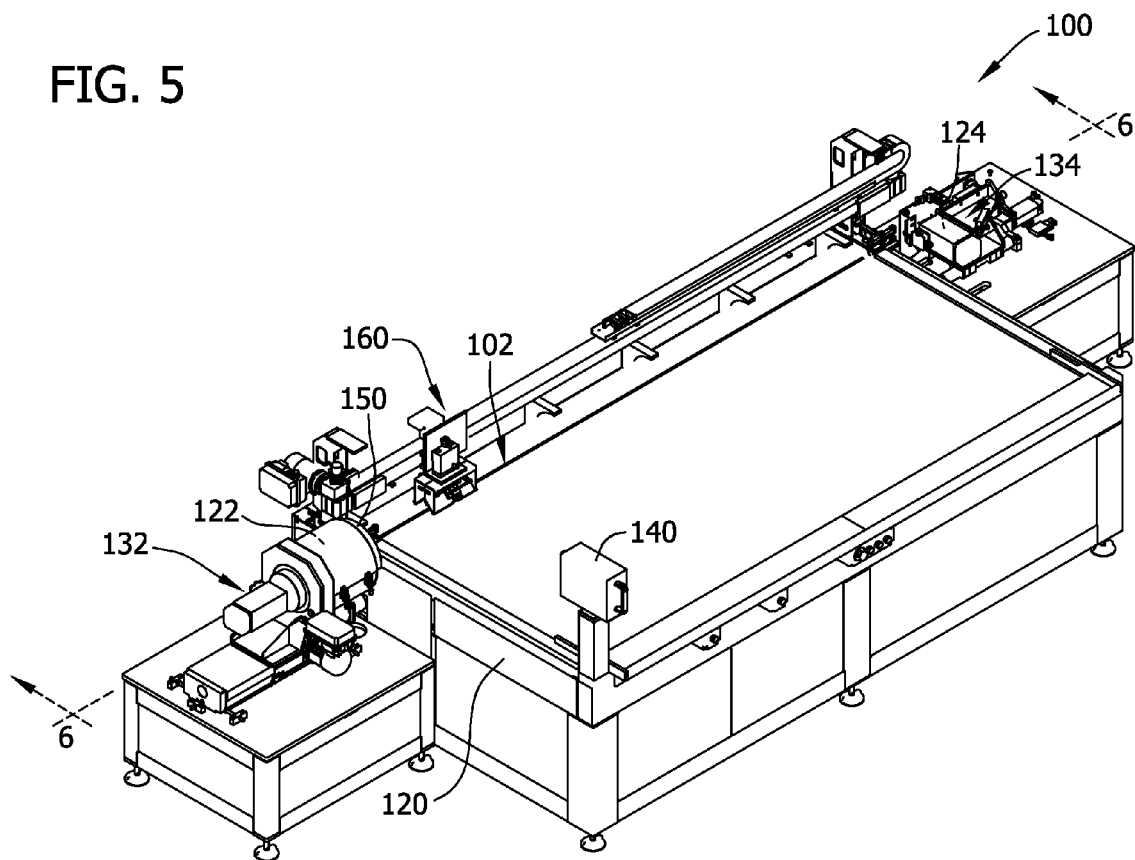


FIG. 6

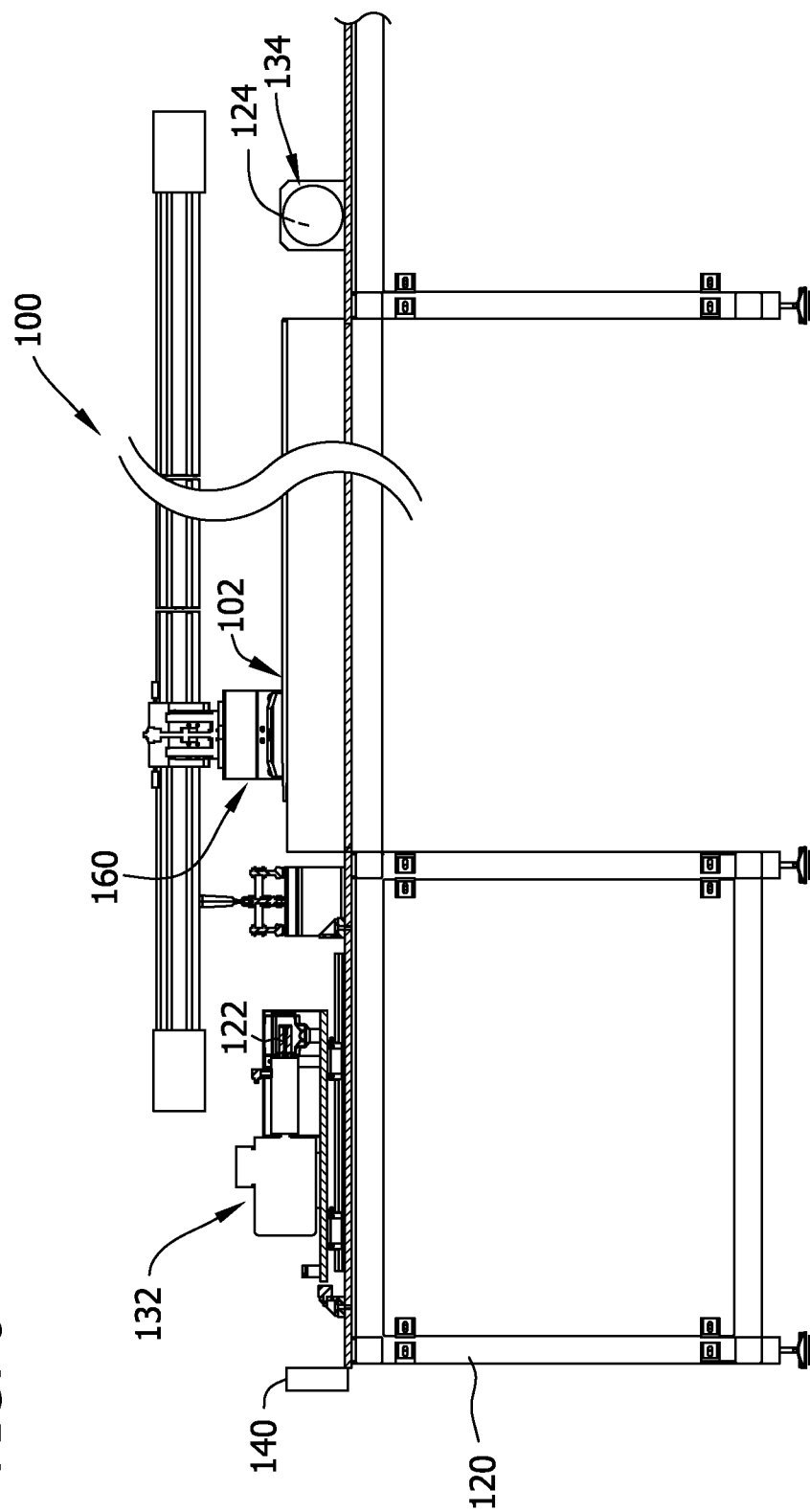


FIG. 7

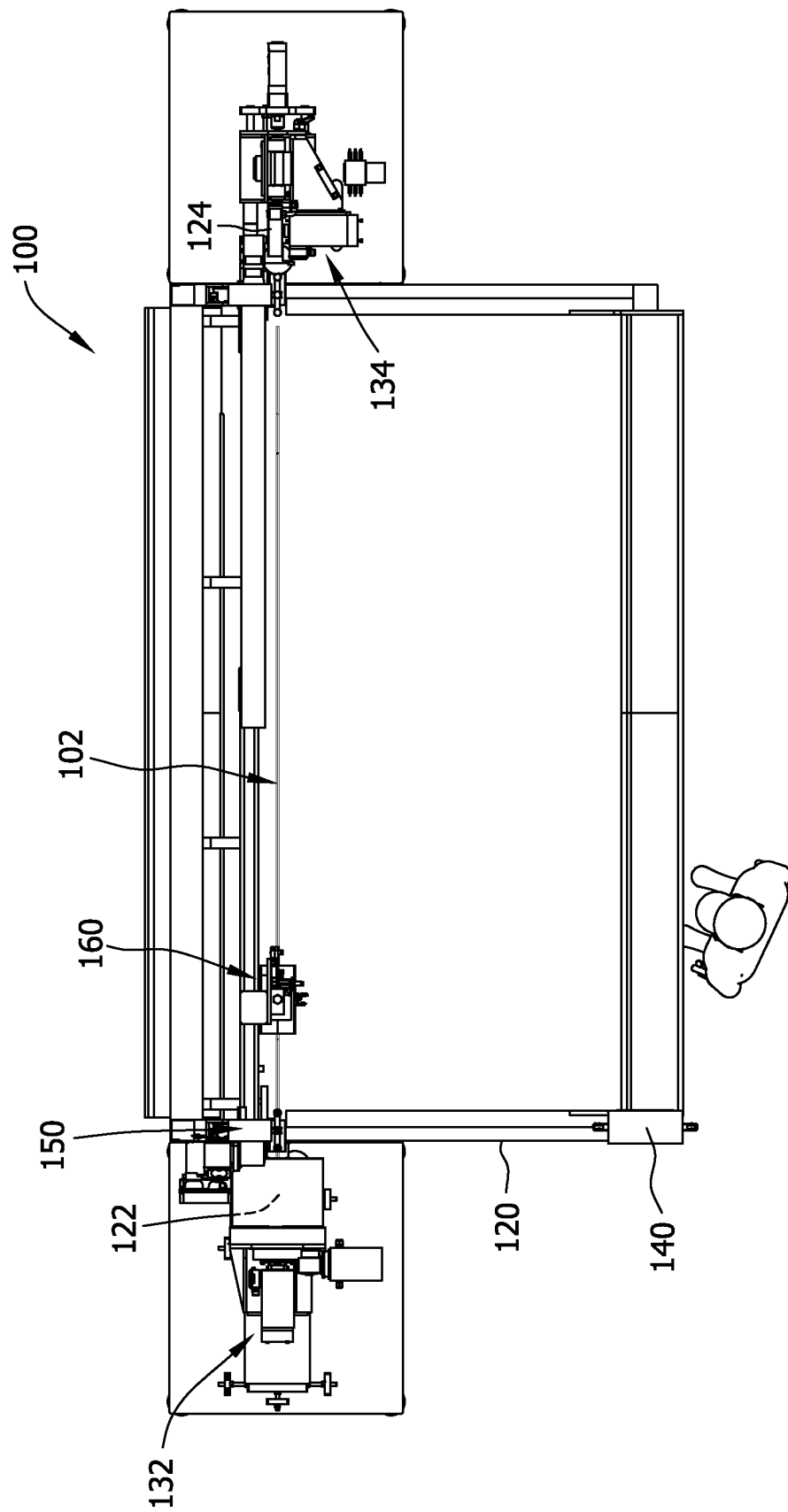
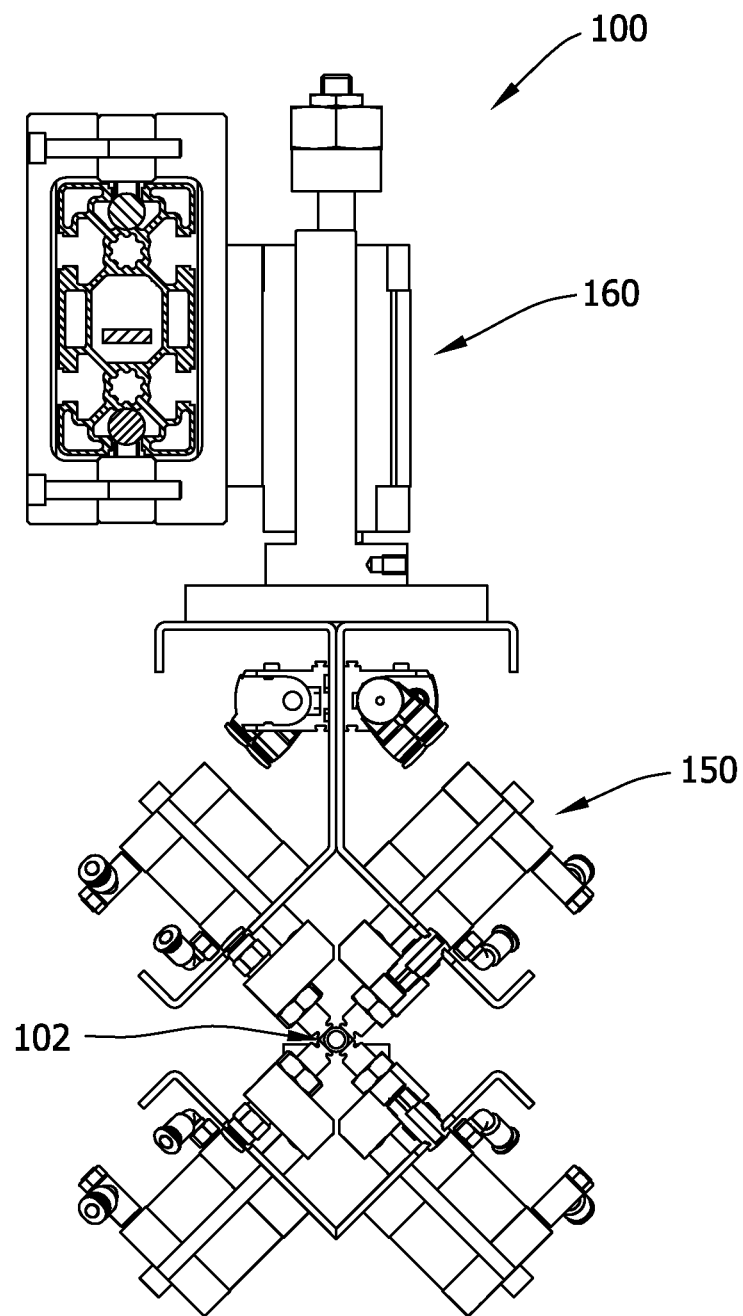


FIG. 8



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METHOD FOR MACHINING SEED RODS FOR USE IN A CHEMICAL VAPOR DEPOSITION POLYSILICON REACTOR

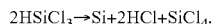
FIELD

This disclosure generally relates to systems and methods for machining silicon and, more specifically, to systems for machining silicon seed rods for use in a chemical vapor deposition reactor.

BACKGROUND

Ultrapure polysilicon used in the electronic and solar industry is often produced through deposition from gaseous reactants via a chemical vapor deposition (CVD) process conducted within a reactor.

One process used to produce ultrapure polycrystalline silicon in a CVD reactor is referred to as a Siemens process. Silicon rods disposed within the reactor are used as seeds to start the process. Gaseous silicon-containing reactants flow through the reactor and deposit silicon onto the surface of the rods. The gaseous reactants (i.e., gaseous precursors) are silane-containing compounds such as halosilanes or monosilanes. The reactants are heated to temperatures above 1000° C. and under these conditions decompose on the surface of the rods. Silicon is thus deposited on the rods according to the following overall reaction:



The process is stopped after a layer of silicon having a predetermined thickness has been deposited on the surface of the rods. The silicon rods are then harvested from the reactor for further processing.

The silicon seed rods used in the reactor are formed from larger blocks or ingots of silicon that are cut by a saw to form the seed rods. The silicon seed rods typically have a circular or square cross-sectional shape. Pairs of silicon seed rods are connected in the reactor at their respective first ends by a silicon bridge rod. The opposing, second ends of the silicon seed rods are connected to a graphite chuck within the reactor.

In some systems, the first ends of the seed rods have a V-shaped or dovetail-like profile. The second ends of the rods have a conical profile to aid in connecting the ends to the graphite chuck. In these systems, an operator uses two separate machines and corresponding machining operations to machine the first and second ends of the seed rods. These machines machine the rods with a rotating grinding wheel and/or rotate the rods.

These systems suffer from a number of shortcomings, one of which is that they require two separate machines to machine one silicon seed rod. That is, one machine is required to machine the first end of the rod and a second machine is required to machine the second end. Moreover, the known systems are ill-equipped to machine rods that are not squares. For example, when the rods are cut from larger ingots into rods they may not have a true square cross-sectional shape. When such rods are mounted in a mandrel of the machines and rotated, the rotational axis of the mandrel may not coincide and instead be misaligned with the effective rotational axis of the rod. Such misalignment may result in poor-quality machining of the rod.

This Background section is intended to introduce the reader to various aspects of art that may be related to various aspects of the present disclosure, which are described and/or claimed below. This discussion is believed to be helpful in providing the reader with background information to facili-

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tate a better understanding of the various aspects of the present disclosure. Accordingly, it should be understood that these statements are to be read in this light, and not as admissions of prior art.

SUMMARY

One aspect is directed to a method for machining a profile into a silicon seed rod using a machine. The silicon seed rod is capable of being used in a chemical vapor deposition polysilicon reactor. The machine comprises a plurality of grinding wheels. The method comprises grinding a v-shaped profile into a first end of the silicon seed rod with one of the plurality of grinding wheels and grinding a conical profile in a second end of the silicon seed rod with another of the plurality of grinding wheels.

Another aspect is directed to a system for machining a profile into a silicon seed rod used in a chemical vapor deposition polysilicon reactor. The system comprises a frame for holding a plurality of silicon seed rods, a first grinding wheel for grinding a v-shaped profile into a first end of the silicon seed rods, and a second grinding wheel for grinding a conical profile into a second end of the silicon seed rods. An optical measurement system is configured for measuring at least one of the first end and the second end of the silicon seed rods. The grinding wheels are controlled based at least in part on an output of the optical measurement system.

BRIEF DESCRIPTION OF THE DRAWINGS

FIG. 1 is a perspective view of an exemplary CVD reactor with an outer cover of the reactor removed and showing silicon deposited on seed rods;

FIG. 2 is a partial schematic view of a pair of silicon seed rods and a chuck used in the reactor of FIG. 1;

FIG. 3 is an enlarged view of a portion of FIG. 2;

FIG. 4 is a side view of FIG. 2;

FIG. 5 is a perspective view of a system for machining silicon seed rods;

FIG. 6 is a front view of the system of FIG. 5;

FIG. 7 is a top view of the system of FIG. 5; and

FIG. 8 is an end view of the system of FIG. 5 with a frame of the system omitted for clarity.

Like reference symbols in the various drawings indicate like elements.

DETAILED DESCRIPTION

The embodiments described herein generally relate to systems and methods for machining silicon seed rods for use in a chemical vapor deposition (CVD) polysilicon reactor. These silicon seed rods are then used during production of polysilicon in the CVD reactor. While reference is made herein to machining silicon seed rods, these systems and methods described herein may also be used to machine other semiconductor and solar materials. An exemplary CVD reactor is shown in FIG. 1 and indicated generally at 10. This reactor 10 depicted in FIG. 1 is shown after completion of the chemical vapor deposition process, and thus the seed rods are not readily visible.

An exemplary system for machining the silicon seed rods 102 is indicated generally at 100 in FIGS. 5 through 8, while the seed rods are shown in greater detail in FIGS. 2-4. FIG. 2 depicts a partial schematic view of a pair of silicon seed rods and a chuck used to connect the rods to a reactor (such as the reactor 10). The silicon seed rods 102 (FIG. 2) may be cut from ingots formed according to any suitable process, such as

the Czochralski process. In the example embodiment, the larger silicon ingots may have a length of up to about 3000 mm and a diameter of up to about 125 mm. The silicon ingots are cut by one or more saws to form the seed rods **102**. The seed rods **102** typically have a length of about 2-3 m, or about 2500 mm, and a square cross-section of about 7 to about 11 mm, or about 9 mm by 9 mm.

Each of the seed rods **102** has a first end **104** and a second end **106**. Pairs of silicon seed rods **102** are connected in the reactor at their respective first ends **104** by a silicon bridge rod **108**. The opposing second ends **106** of the silicon seed rods **102** are connected to a graphite chuck **110** within the reactor.

As described in greater detail below, the first ends **104** of the seed rods **102** are machined such that they have a V-shaped or dovetail-like profile **114** (e.g., a dovetail joint). This profile **114** of the first ends **104** is shown in FIG. 4. The profile in the first end **104** forms a channel **112** in which the bridge rod **108** is received. As shown in FIG. 3, the second ends **106** of the rods **102** are machined to have a conical profile **116** to facilitate connecting the second ends to the graphite chuck **110**. In the depiction of FIG. 3, second end **106** is shown spaced from the chuck **110** to better show the conical profile **116**. This second end **106** is thereafter moved (downward in FIG. 3) so that at least a portion of the second end **106** is received within an opening in the chuck **110**. The conical profile **116** of the second end **106** facilitates correct placement of the seed rod **102** within the opening in the chuck **110**.

As shown in FIGS. 5-8, the system **100** has a frame **120** for holding the seed rods. A first grinding wheel **122** and a second grinding wheel **124** are positioned adjacent the frame **120**. The grinding wheels **122**, **124** are used to machine the profiles described above into the ends **104**, **106** of each silicon seed rod **102**. In the example embodiment, the grinding wheels **122**, **124** are of the ordinary abrasive composite type which includes a material having a composition (e.g., diamond coated) operable to machine the desired profiles in the ends **104**, **106** of each seed rod **102**.

Each of the grinding wheels **122**, **124** is connected to one of a respective first drive source **132** and second drive source **134**, which are in turn connected either directly to the frame **120** or by additional structures. These additional structures can comprise actuators (e.g., linear, pneumatic, or hydraulic actuators) operable to move the grinding wheels **122**, **124** with respect to the frame **120**. Alternatively, or in addition to, other actuators may be connected to the frame **120** to move the silicon seed rods **102** with respect to the frame. In these embodiments, the grinding wheels **122**, **124** may remain stationary with respect to the frame and the seed rods are movable. Alternatively, both the seed rods **102** and the grinding wheels **122**, **124** may be movable.

In the example embodiment, the drive sources **132**, **134** are electric motors while in other embodiments the drive sources may be any other mechanism capable of rotating the grinding wheels. Examples include hydraulic or pneumatic motors.

A suitable conveyance mechanism **160** is positioned adjacent the frame **120** for moving the silicon seed rods **102** with respect to the frame. The conveyance mechanism **160** may comprise one or more actuators, conveyors, loaders and other suitable mechanisms and associated control mechanisms.

Operation of the drive sources **132**, **134**, and hence operation of the grinding wheels **122**, **124**, is controlled by a control system **140** (shown schematically in FIG. 5). The control system **140** can comprise, among other components, one or more processors, programmable logic controllers (PLCs), computer readable storage mediums, and input/output devices. The control system **140** controls operation of the grinding wheels **122**, **124** by controlling the flow of electricity

(power) to the respective drive sources **132**, **134** connected to the grinding wheels. The control system **140** is communicatively coupled to the conveyance mechanism **160** to control its operation.

In the example embodiment, the control system **140** includes an optical measurement system **150**. This optical measurement system **150** measures the second end **104** of the silicon seed rods **102**. The optical measurement system **150** uses one or more lasers or other suitable optical devices to measure the shape (i.e., profiles **116**) of the ends of the seed rods **102**. In one embodiment, only the shape of the second end is measured. Four lasers are used to determine the shape of the cone or conical profile at four points. This measurement occurs after the ends **104**, **106** are machined by the grinding wheels.

The optical measurement system **150** is connected or communicatively coupled to the control system **140** by any suitable wired or wireless communication system. The optical measurement system **150** is operable to send as an output the shape of the second end **106** of the seed rod **102** to the control system **140**. Based on this received output, the control system **140** is operable to control operation of the drive sources **134** (and thus the grinding wheels). In this embodiment, if the four points of the cone are determined to be within tolerance, the grinding operation is complete. If they are not within tolerance, grinding may continue or the rod may be rejected (indicating the rod is defective). Note that if multiple rods are rejected, the control system may indicate to the operator that maintenance or repair of the grinding wheel is needed. Other methods may also be used by the control system **140** to control operation.

Control of the operation of the drive sources **132**, **134** can include altering the rotational velocity of the drive sources and thus the rotational velocity of the grinding wheels **122**, **124** attached thereto. Such control can also include the adjustment of the position of the seed rods **102** and/or the position of the grinding wheels **122**, **124** with respect to the frame **120**. Actuators or other suitable devices can be used to move or adjust the position of the seed rods **102** (e.g., the conveyance system **160**) and/or grinding wheels **122**, **124** (or the drive sources **132**, **134**). Such actuators can be connected to the control system **140** such that the control system can control their operation. Note that a control system of another embodiment may control the machining of the first end by the first grinding wheel based at least in part on the output of the optical measure system.

During use of the system **100**, the seed rods **102** are first loaded on the frame **120**. One of the rods **102** is then moved by the conveyance system **160** to a position such that the first end **104** of the rod is adjacent the first grinding wheel **122**. The first grinding wheel **122** is then used to grind the v-shaped (i.e., dove tail) profile **114** into the first end **104** of the rod **102**.

The seed rod **102** is then moved by the conveyance system **160** to a position such that the second end **106** of the rod is adjacent the second grinding wheel **124**. Alternatively, the seed rod **102** may remain substantially stationary after being machined by the first grinding wheel **122**.

The second grinding wheel **124** is then used to grind the conical profile **116** into the second end **106** of the seed rod **102**. The control system **140** may control the machining of the second end **106** by the second grinding wheel **124** based at least in part on the output of the optical measurement system **150**. The conveyance system **160** may then move the rod **102** to another position away from the grinding wheels **122**, **124** and/or frame **120**. The process is then repeated for each of the remaining seed rods **102**. In other embodiments, the process

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may be reversed such that the second end **106** of the seed rod **102** is machined prior to or contemporaneously as the first end **104**.

When introducing elements of the present invention or the embodiment(s) thereof, the articles “a”, “an”, “the” and “said” are intended to mean that there are one or more of the elements. The terms “comprising”, “including” and “having” are intended to be inclusive and mean that there may be additional elements other than the listed elements. The use of terms indicating a particular orientation (e.g., “top”, “bottom”, “side”, etc.) is for convenience of description and does not require any particular orientation of the item described.

As various changes could be made in the above constructions and methods without departing from the scope of the invention, it is intended that all matter contained in the above description and shown in the accompanying drawing[s] shall be interpreted as illustrative and not in a limiting sense.

What is claimed is:

1. A method for machining a profile into a silicon seed rod using a machine, the silicon seed rod used in a chemical vapor deposition polysilicon reactor, the machine comprising a plurality of grinding wheels, the method comprising:

providing a silicon seed rod having a first end and an opposing second end;

grinding a v-shaped profile into an end face of the first end of the silicon seed rod with one of the plurality of grinding wheels; and

grinding a conical profile in the second end of the silicon seed rod with another of the plurality of grinding wheels.

2. The method of claim **1** wherein a rate of the grinding of the conical profile in the second end is controlled based at least in part on an output of an optical measurement system.

3. The method of claim **2** wherein the optical measurement system measures an angle of the conical profile and outputs the measurement to the system.

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4. The method of claim **1** wherein at least a portion of the second end is shaped to be received within a chuck of the reactor.

5. The method of claim **1** further comprising loading a seed rod into the machine.

6. The method of claim **5** wherein the seed rod is moved by a conveyance system so that the first end comes into contact with one of the plurality of grinding wheels.

7. The method of claim **6** wherein the seed rod is moved by the conveyance system so that the second end comes into contact with another of the plurality of grinding wheels.

8. The method of claim **1** wherein the silicon seed rod is one of a plurality of silicon seed rods, the method further comprising loading the plurality of seeds rods into the machine, and moving one of the plurality of seed rods using a conveyance system such that a first end of the silicon seed rod comes into contact with one of the plurality of grinding wheels.

9. The method of claim **1** further comprising measuring at least one of the v-shaped profile and the conical profile with an optical measurement system, and rejecting the silicon seed rod based at least in part on an output of the optical measurement system.

10. The method of claim **1** wherein the v-shaped profile forms a channel configured to receive a bridge rod.

11. The method of claim **1** wherein the silicon seed rod has a length of between about 2,000 millimeters (mm) and about 3,000 mm.

12. The method of claim **1** wherein the silicon seed rod has a cross-sectional area of between about 70 mm² and about 90 mm².

13. The method of claim **1** wherein the silicon seed rod has a square-shaped cross-section.

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